

PRELIMINARY SHEET

TTL02, TTL04, TTL06, TTL08, TTL12, TTL20, TTL25

±5%, ±1%, ±0.5%

High Power Thin Film Current Sensor

Size:0201,0402,0603,0805,1206,2010,2512



*Contents in this sheet are subject to change without prior notice.

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FEATURES

- 1. Extra high power rating and low TCR.
- 2. Extra low resistance and high precision.
- 3. High component and equipment reliability
- 4. Low resistances applied to current sensing
- 5. RoHS compliant & Halogen Free.
- 6. Suitable for lead free soldering.

APPLICATIONS

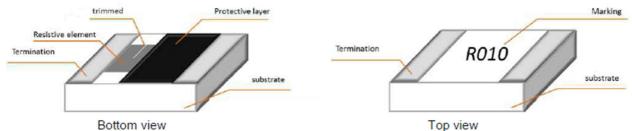
- Current sensor
- Medical equipment
- Measuring instrument
- Communication device
- Power supply

Computer

DESCRIPTION

This specification describes TTL series current sensor – Extra high power and low TCR with lead-free terminations made by metal film with substrate.







Quick Reference Data

					Fu	ınction	al code	Э				
Series	Size Code				Pow	/er				TCR	Resistance Range	Resistance Tolerance
		G	Н	I	J	K	М	Р	Q			
	0201 (0603)	1/10W	1/8W	1/5W	1/4W	1/3W				350ppm/℃	5~20m Ω	
	0402 (1005)		1/8W	1/5W	1/4W	1/3W	1/2W			150ppm/℃	2.5~20m Ω	
	0603 (1608)			1/5W	1/4W	1/3W	1/2W			75ppm/℃	5~20m Ω	.0.50/
	0805 (2012)				1/4W	1/3W	1/2W	15		75 ppm/℃	5~20m Ω	$\pm 0.5\%$ (>10m Ω)
TTL	1206 (3216)			档	1/4W	1/3W	1/2W	1W	H	75ppm/ ℃	5~20m Ω	±1%
	2010 (5025)	/1	和		人扩	以仅	.[J]	1W	2W	50ppm/°C 75ppm/°C 100ppm/°C	5~20m Ω	±5%
	2512 (6342)		#	#	F		5/	1W	2W	50ppm/°C 75ppm/°C 100ppm/°C	5~20m Ω	

PASSIVE SYSTEM ALLIANCE

Note:

- 1. This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2. Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by $RCWV = \sqrt{Rated Power \times Resistance Value}$
- 3. Operating Temperature Range 0201/0402 : -55°C to +125°C

0603/0805/1206/2010/2512: -55°C to +170°C



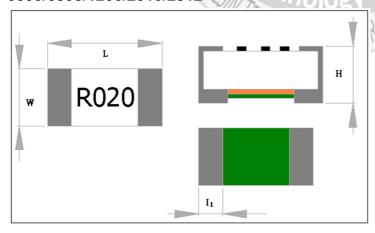
Preliminary Sheet

DIMENSIONS:(unit:mm)

Туре	Resistance Range	L(mm)	W(mm)	H(mm)	l1(mm)
TTL02	5~20m Ω	0.60±0.03	0.31±0.04	Max:0.30	0.14±0.16
TTL04	2.5~20m Ω	1.00±0.10	0.55±0.10	Max:0.35	0.25±0.10
TTL06	5~20mΩ	1.60±0.20	0.76±0.25	0.56±0.25	0.38±0.25
TTL08	5~20mΩ	2.03±0.25	1.27±0.25	0.56±0.25	0.38±0.25
TTL12	5~20mΩ	3.20±0.25	1.60±0.25	0.64±0.25	0.51±0.25
TTL20	5~20mΩ	5.08±0.25	2.54±0.25	0.64±0.25	0.51±0.25
TTL25	5~20m Ω	6.35±0.25	3.18±0.25	0.64±0.25	0.76±0.25

0201/0402 L W

0603/0805/1206/2010/2512



Marking 0201/0402(No Marking)



0603/0805(3 digits)



020=20m Ω

1206/2010/2512(4 digits)

R020

R020=20m Ω

FUNCTIONAL DESCRIPTION PASSIVE

Product characterization

Standard values of nominal resistance are taken from the E96 & E24 series for resistors with a tolerance of $\pm 5.0\%, \pm 1.0\%$. The values of the E24/E96 series are in accordance with "IEC publication 60063".

Preliminary Sheet

DERATING

The power that the resistor can dissipate depends on the operating temperature; see Fig.1&Fig2

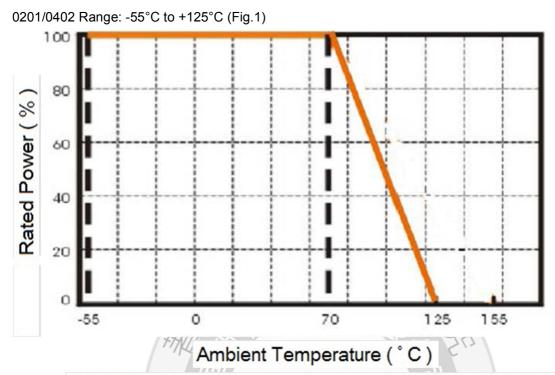


Fig.1 Maximum dissipation in percentage of rated power

As a function of the ambient temperature

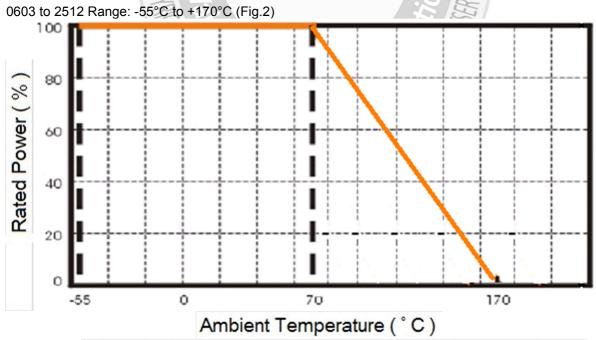


Fig.2 Maximum dissipation in percentage of rated power

As a function of the ambient temperature

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MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.

SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering profile and condition that provide reliable joints without any damage are given in Fig 3. and Table 1.

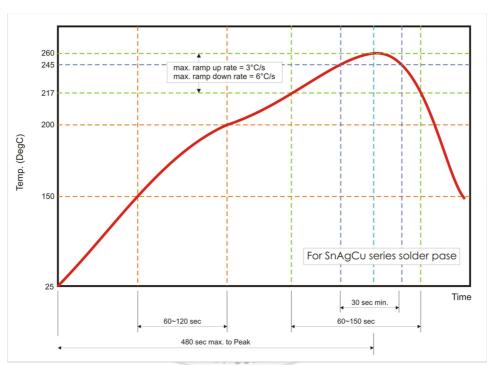


Fig. 3 Infrared soldering profile for Chip Resistors

Table 1. Infrared soldering condition for Chip Resistors

Temperature Condition	Exposure Time
Average ramp-up rate (217°C to 260°C)	Less than 3°C/second
Between 150 and 200°C	Between 60-120 seconds
> 217°C	Between 60-150 seconds
Peak Temperature	260°C +0/-5°C
Time within 245°C	Min. 30 seconds
Ramp-down rate (Peak to 217°C)	Less than 6°C/second
Time from 25°C to Peak	No greater than 480 seconds

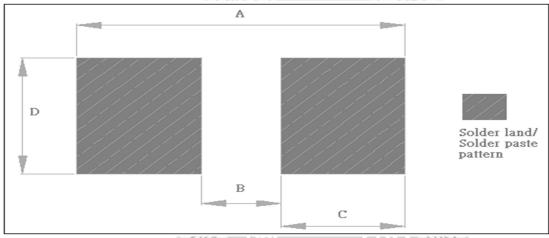
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CATALOGUE NUMBERS

TTL	02	Q	N	XXXX	F	Т	L
Type code Low Resistance	Size code 02: 0201 04: 0402 06: 0603 08: 0805 12: 1206 20: 2010 25: 2512	Power Rating Q:2W P:1W M:1/2W K:1/3W J:1/4W I:1/5W H:1/8W G:1/10W	TCR N:50ppm/°C O:75ppm/°C P:100ppm/°C Q:150ppm/°C R:200ppm/°C U:350ppm/°C	Resistance e.g. : R020 = $20m\Omega$ R005 = $5m\Omega$ R2L5 = $2.5m\Omega$	D: 0.5% F: 1.0% J: 5.0%	Packaging code T: 7" Taped & Reeled	Termination Code L: Sn base (lead-free)

Recommend Solder Pad Dimensions



	· V//// /'s		1 146		
Type	Resistance Range	A(mm)	B(mm)	C(mm)	D(mm)
TTL02	5~20m Ω	1.00	0.30	0.35	0.40
TTL04	2.5~20m Ω	2.00	0.40	0.80	0.60
TTL06	5~20m Ω	2.52	0.50	1.01	1.01
TTL08	5~20m Ω	2.54	0.50	1.02	1.27
TTL12	5~20m Ω	3.90	0.76	1.57	1.78
TTL20	5~20m Ω	6.10	3.30	1.40	3.05
TTL25	5~20m Ω	7.36	4.06	1.65	3.68



TEST AND REQUIREMENTS(JIS C 5201-1: 1998)

		REQUIREMENT		
TEST	PROCEDURE	Resistor		
DC resistance IEC 60115-1 / JIS C 5201-1 , Clause 4.5	D: ±0.5%,F: ±1%, G: ±5%	Within the specified tolerance		
Temperature Coefficient of Resistance(T.C.R)	Natural resistance change per change in degree centigrade. $\frac{R_2-R_1}{R_1(t_2-t_1)}\times 10^6 \end{substitute} \begin{substitute}(c) (ppm/C) \\ R_1: Resistance at reference temperature \\ R_2: Resistance at test temperature \\ t_1: 20^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C} \\ t_2: 125^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C} \end{substitute}$	Refer to " QUICK REFERENCE DATA"		
Short time overload (S.T.O.L) IEC60115-1 4.13	5 times of rated power for 5 seconds at room temperature	No visible damage ±(1.0%+0.0005Ω)		
Resistance to soldering heat(R.S.H) MIL-STD-202G- method 210F IEC 60115-1 4.18	Condition B, no pre-heat of samples Leadfree solder, 260 °C, 10 seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	No visible damage $\pm (0.5\% + 0.0005\Omega)$		
Solderability IPC/JEDEC J-STD-002B test B	SMD conditions: 1st step: method B, aging 4 hours at 155 °C dry heat ∈ 2nd step: leadfree solder bath at 245± 3 °C Dipping time: 3± 0.5 seconds	good tinning (>95% covered) no visible damage		
Thermal Shock MIL-STD-202G- method 107	-55/+125 °C Note: Number of cycles required is 300. Devices mounted Maximum transfer time is 20 seconds. Dwell time is 15 minutes. Air – Air	±(1.0%+0.0005Ω)		
Endurance MIL-STD-202G- method 108 IEC 60115-1 4.25.1	70±2°C, 1000 hours, loaded with RCWV,,1.5 hours on and 0.5 hours off	±(1.0%+0.0005Ω)		
Bias Humidity MIL-STD-202 Method 103	1,000 hours at 85°C/85%R.H. 10% of operating power, no condensation on the devices, circulating air.	±(1.0%+0.0005Ω)		
Bending Strength IEC60115-1 4.33	Device mounted on PCB test board as described, only 1 board bending required Bending for 0201: 3mm 0402 and above: 2mm Holding time: minimum 60 seconds	±(1.0%+0.0005Ω)		
High Temperature Exposure MIL-STD-202G- method 108 IEC 60115-1 4.25.3	-	±(1.0%+0.0005Ω)		



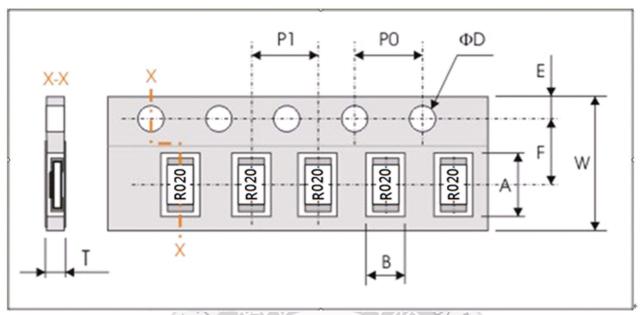
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Moisture Resistance	Each temperature / humidity cycle is defined at 8 hours	$\pm (0.5\% + 0.0005 \Omega)$
MIL-STD-202G-	(method 106F), 3 cycles / 24 hours for 10d with 25 °C / 65	
method 106	°C 95% R.H, without steps 7a & 7b, unpowered	
	Parts mounted on test-boards, without condensation on	
	parts	
	Measurement at 24± 2 hours after test conclusion	



PACKAGING

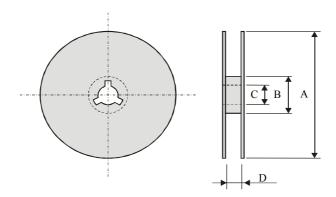
Paper Tape specifications (unit: mm)



	14/17						
Series No.	Α	В	w	F	E		
TTL02	0.720±0.05	0.42±0.05	8.00±0.30	3.50±0.05	1.75±0.10		
TTL04	1.20±0.10	0.7±0.10	8.00±0.30	3.50±0.05	1.75±0.10		
TTL06	1.90±0.20	1.10±0.20	8.00±0.30	3.50±0.20	1.75±0.10		
TTL08	2.40±0.20	1.65±0.20	8.00±0.30	3.50±0.20	1.75±0.10		
TTL12	3.60±0.20	2.00±0.20	8.00±0.30	3.50±0.20	1.75±0.10		
TTL20	5.50±0.20	2.80±0.20	12.00±0.30	5.50±0.10	1.75±0.10		
TTL25	6.90±0.20	3.60±0.20	12.00±0.30	5.50±0.10	1.75±0.10		
	FOUND STONE HALL						

		1 4/101	- 00 1711 1111	
Series No.	P1	P0	ΦD	Т
TTL02	2.00±0.10	4.00±0.10	Φ 1.50 $^{+0.1}_{-0.0}$	0.4±0.05
TTL04	2.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	0.40±0.05
TTL06	4.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	0.65±0.05
TTL08	4.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	Max. 1.0
TTL12	4.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	Max. 1.0
TTL20	4.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	Max 1.2
TTL25	4.00±0.10	4.00±0.10	Ф1.50 ^{+0.1} _{-0.0}	Max 1.2

Reel Dimensions:



Symbol	Α	В	С	D
(unit : mm)	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	9.0±0.5

Taping Quantity

- Chip resistors 4,000 pcs per reel (TTL25, TTL20)
- Chip resistors 5,000 pcs per reel (TTL12, TTL08, TTL06)
 Chip resistors 10,000 pcs per reel (TTL04)
 Chip resistors 15,000 pcs per reel (TTL02)

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